MSKSEMI















ESD

TVS

TSS

MOV

GDT

PLED

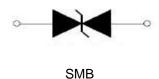
Broduct data sheet

PxxxxSB-MS









Features

Low capatcitance Cannot be damaged by voltage Will not fatigue Eliminate voltage overshoot Glass passivated junction Halogen free and RoHS compliant

Mechanical Data

CASE: SMB(DO-214AA) Molded Plastic UL Flammability Classification Rating 94V0 Mounting Position:Any

Maximum Ratings & Thermal Characteristics

(Ratings at 25°C ambient temperature unless otherwise specified.)

Parameter	Symbol	Value	Units	Remarks
Peak Pulse Voltage	V_{PP}	4000	V	10/700us
Peak Pulse Current	Ірр	80	А	10/1000us
Peak Pulse Current	I _{PK}	250	Α	8/20us
Peak One-cycle Surge Current	I _{TSM}	25	А	60Hz
Rate of Rise of Current	di/dt	500	A/us	
Typical Thermal Resistance Junction to Lead	$R_{ heta JL}$	20	°C/W	
Typical Thermal Resistance Junction to Ambient	$R_{ heta JA}$	100	°C/W	
Operating Temperature Range	TJ	-40 to 150	°C	
Storage Temperature Range	T _{STG}	-55 to 150	°C	

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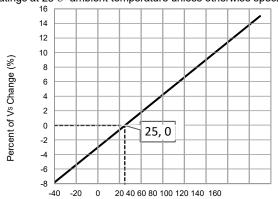
Electrical Characteristics

P/N	Mark	V _S @100KV/S V MAX	I _{S_LMT} mA	V _T @ I _T V MAX	I _T	I _D @ V _D uA MAX	V _D V	C _O @1MHz,2V _{DC} pF TYP	I _H mA TYP
P0080SB-MS	P008B XXXX	25	500	4	2.2	5	6	84	40
P0220SB-MS	P02B XXXX	30	500	4	2.2	5	15	84	40
P0300SB-MS	P03B XXXX	40	500	4	2.2	5	25	80	40
P0640SB-MS	P06B XXXX	77	800	4	2.2	5	58	76	120
P0720SB-MS	P07B XXXX	88	800	4	2.2	5	65	76	120
P0900SB-MS	P09B XXXX	98	800	4	2.2	5	75	76	120
P1100SB-MS	P11B XXXX	130	800	4	2.2	5	90	72	120
P1300SB-MS	P13B XXXX	160	800	4	2.2	5	120	72	120
P1500SB-MS	P15B XXXX	180	800	4	2.2	5	140	68	120
P1800SB-MS	P18B XXXX	220	800	4	2.2	5	170	64	120
P2300SB-MS	P23B XXXX	260	800	4	2.2	5	190	60	120
P2600SB-MS	P26B XXXX	300	800	4	2.2	5	220	56	120
P3100SB-MS	P31B XXX	350	800	4	2.2	5	275	52	120
P3500SB-MS	P35B XXXX	400	800	4	2.2	5	320	48	120
P4500SB-MS	P45B XXXX	530	800	4	2.2	5	400	36	120

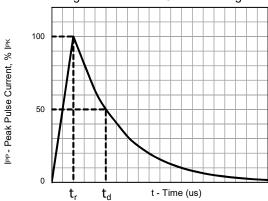
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Ratings and Characteristic Curves (Ratings at 25°C ambient temperature unless otherwise specified).



 T_J - Junction Temperature (°C) Fig.1 - Peak Pulse Current Rating



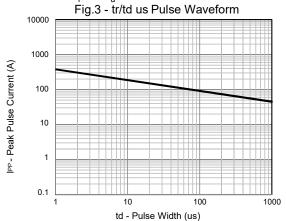


Fig.5 - Peak Pulse Current Rating

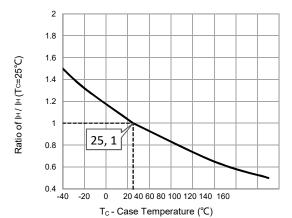
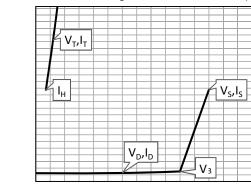


Fig.2 - Normalized DC Holding Current vs. Case Temperature



Current (A)

Voltage (V) Fig.4 - VI Curve 100 Co - Typical Off-state Capacitance (pF) 80 60 40 20 V_B- Breakdown Voltage (V)
Fig.6 - Typical Off-state Capacitance

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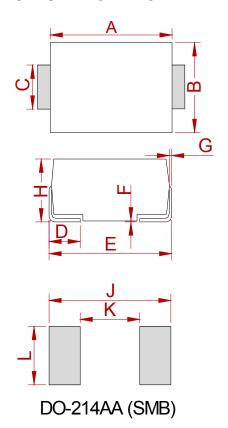








PACKAGE MECHANICAL DATA



	Dimensions				
Ref.	Millir	neters	Inches		
	Min.	Max.	Min.	Max.	
Α	4.25	4.75	0.167	0.187	
В	3.30	3.94	0.130	0.155	
С	1.85	2.21	0.073	0.087	
D	0.76	1.52	0.030	0.060	
Е	5.08	5.59	0.200	0.220	
F	0.051	0.203	0.002	0.008	
G	0.15	0.31	0.006	0.012	
Н	2.11	2.44	0.083	0.096	
J	6.80		0.270		
K		2.60		0.100	
L	2.40		0.090		

REEL SPECIFICATION

P/N	PKG	QTY
PxxxxSB-MS	SMB	3000



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